

REMARKS/ARGUMENTS

Applicants first wish to thank Examiner Norris for his indication of allowable subject matter. Reconsideration of the above-identified application is respectfully requested in view of the foregoing amendments and the following remarks. Claims 10 and 11 were canceled. Claim 1 was amended. Claims 1 - 9 and 12 - 17 remain in the case.

Claims 1 - 3, 7, and 11 - 17 were rejected under 35 U.S.C. §102(e) as being anticipated by United States Patent No. 6,428,328 for METHOD OF MAKING A CONNECTION TO A MICROELECTRONIC ELEMENT, issued August 6, 2002 to Belgacem Haba et al. (U.S.). Claim 1 has been amended to incorporate the allowable subject matter of claim 10. Consequently, the rejection of claims 1 - 3, 7, and 12 - 17 (claim 11 has been canceled) under 35 U.S.C. §102(e) is overcome.

Claim 4 was rejected under 35 U.S.C. §103(a) as being unpatentable over HABA in view of United States Patent No. 6,219,253 for MOLDED ELECTRONIC PACKAGE, METHOD OF PREPARATION USING BUILD-UP TECHNOLOGY AND METHOD OF SHIELDING, issued April 17, 2001 to William J. Green. Because claim 1 has been amended to overcome HABA et al., Applicants believe that the obviousness rejection of claim 4 is likewise now overcome.

Claim 5 was rejected under 35 U.S.C. §103(a) as being unpatentable over HABA in view of United States Patent No. 5,984,691 for FLEXIBLE CIRCUITIZED INTERPOSER WITH APERTURED MEMBER AND METHOD FOR MAKING SAME, issued November 16, 1999 to William Louis Brodsky et al. The amendment of claim 1 is believed to also overcome the rejection of claim 5 as being unpatentable over HABA in view of BRODSKY et al.

Claim 6 was rejected under 35 U.S.C. §103(a) as being unpatentable over HABA in view of United States Patent No. 6,332,782 for SPATIAL TRANSFORMATION INTERPOSER FOR ELECTRONIC PACKAGING, issued December 25, 2001 to Raschid J. Bezama et al. The amendment of claim 1 is believed to also overcome the rejection of claim 6 as being unpatentable over HABA in view of BEZAMA et al.

Claims 8 and 9 were rejected under 35 U.S.C. §103(a) as being unpatentable over HABA in view of United States Patent No. 4,553,192 for HIGH DENSITY PLANAR INTERCONNECTED INTEGRATED CIRCUIT PACKAGE, issued November 12, 1985 to Robert Babuka et al. The amendment of claim 1 is believed to also overcome the rejection of claims 8 and 9 as being unpatentable over HABA in view of BABUKA et al.

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In view of the foregoing amendments and remarks,
Applicants respectfully request that claims 1 - 9 and 12 - 17
be allowed and the application be passed to issue.

Dated: 9/29/03

Respectfully submitted,
SALZMAN & LEVY

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